

Title (en)

METHOD AND DEVICE FOR MICROMACHINING A WORKPIECE BY MEANS OF LASER RADIATION

Title (de)

VERFAHREN UND VORRICHTUNG ZUR MIKROBEARBEITUNG EINES WERKSTÜCKS MIT LASERSTRAHLUNG

Title (fr)

PROCEDE ET DISPOSITIF DE MICRO-USINAGE D'UNE PIECE A USINER AU MOYEN D'UN RAYONNEMENT LASER

Publication

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Application

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Abstract (en)

[origin: WO03018248A1] The invention relates to a method for micromachining a workpiece (3), especially for producing a borehole in the workpiece (3), by means of ultrashort-pulse laser radiation. According to the invention, a sacrificial layer (7) is applied to a surface of the workpiece (3) in a fixed manner. Ultrashort laser pulses are then generated, said pulses penetrating the sacrificial layer (7) and removing material from the workpiece (3). The sacrificial layer (7) is removed once a sufficient amount of material has been removed from the workpiece (3).

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